# **Complementary Dual General Purpose Amplifier Transistor**

## **PNP and NPN Surface Mount**

#### **Features**

• High Voltage and High Current:  $V_{CEO} = 50 \text{ V}$ ,  $I_C = 200 \text{ mA}$ 

• High  $h_{EE}$ :  $h_{EE} = 200 \sim 400$ 

• Moisture Sensitivity Level: 1

• ESD Rating

• Human Body Model: 3A

• Machine Model: C

• S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable

• These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant\*

#### **MAXIMUM RATINGS** $(T_A = 25^{\circ}C)$

Rating	Symbol	Value	Unit
Collector-Base Voltage	V <sub>(BR)CBO</sub>	60	Vdc
Collector–Emitter Voltage	V <sub>(BR)CEO</sub>	50	Vdc
Emitter-Base Voltage	V <sub>(BR)EBO</sub>	7.0	Vdc
Collector Current – Continuous	I <sub>C</sub>	200	mAdc

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

#### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Power Dissipation	P <sub>D</sub>	380	mW
Junction Temperature	TJ	150	°C
Storage Temperature	T <sub>stg</sub>	-55 to +150	°C

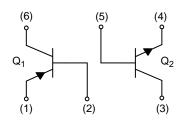


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**CASE 318F** STYLE 3



#### MARKING DIAGRAM



R9

= Specific Device Code

= Date Code

= Pb-Free Package

#### ORDERING INFORMATION

Device	Package	Shipping <sup>†</sup>
HN1B01FDW1T1G	SC-74 (Pb-Free)	3,000/Tape & Reel
SHN1B01FDW1T1G	SC-74 (Pb-Free)	3,000/Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

June, 2016 - Rev. 4

<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

Q1: PNP
ELECTRICAL CHARACTERISTICS (T<sub>A</sub> = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
Collector–Emitter Breakdown Voltage (I <sub>C</sub> = 2.0 mAdc, I <sub>B</sub> = 0)	V <sub>(BR)CEO</sub>	-50	-	Vdc
Collector–Base Breakdown Voltage ( $I_C = 10 \mu Adc, I_E = 0$ )	V <sub>(BR)</sub> CBO	-60	-	Vdc
Emitter–Base Breakdown Voltage ( $I_E = 10 \mu Adc, I_C = 0$ )	V <sub>(BR)EBO</sub>	-7.0	-	Vdc
Collector–Base Cutoff Current $(V_{CB} = 45 \text{ Vdc}, I_E = 0)$	I <sub>CBO</sub>	-	-0.1	μAdc
	I <sub>CEO</sub>	- - -	-0.1 -2.0 -1.0	μAdc μAdc mAdc
DC Current Gain (Note 1) (V <sub>CE</sub> = 6.0 Vdc, I <sub>C</sub> = 2.0 mAdc)	h <sub>FE</sub>	-200	-400	-
Collector–Emitter Saturation Voltage (I <sub>C</sub> = 100 mAdc, I <sub>B</sub> = 10 mAdc)	V <sub>CE(sat)</sub>	_	-0.3	Vdc

#### Q2: NPN

## **ELECTRICAL CHARACTERISTICS** ( $T_A = 25^{\circ}C$ unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
Collector–Emitter Breakdown Voltage $(I_C = 2.0 \text{ mAdc}, I_B = 0)$	V <sub>(BR)CEO</sub>	50	-	Vdc
Collector–Base Breakdown Voltage ( $I_C = 10 \mu Adc$ , $I_E = 0$ )	V <sub>(BR)CBO</sub>	60	-	Vdc
Emitter–Base Breakdown Voltage ( $I_E = 10 \mu Adc, I_C = 0$ )	V <sub>(BR)EBO</sub>	7.0	-	Vdc
Collector–Base Cutoff Current $(V_{CB} = 45 \text{ Vdc}, I_E = 0)$	Ісво	-	0.1	μAdc
Collector–Emitter Cutoff Current $(V_{CE} = 10 \text{ Vdc}, I_B = 0)$ $(V_{CE} = 30 \text{ Vdc}, I_B = 0)$ $(V_{CE} = 30 \text{ Vdc}, I_B = 0, T_A = 80^{\circ}\text{C})$	I <sub>CEO</sub>	- - -	0.1 2.0 1.0	μAdc μAdc mAdc
DC Current Gain (Note 1) (V <sub>CE</sub> = 6.0 Vdc, I <sub>C</sub> = 2.0 mAdc)	h <sub>FE</sub>	200	400	-
Collector–Emitter Saturation Voltage (I <sub>C</sub> = 100 mAdc, I <sub>B</sub> = 10 mAdc)	V <sub>CE(sat)</sub>	-	0.25	Vdc

<sup>1.</sup> Pulse Test: Pulse Width  $\leq$  300  $\mu$ s, D.C.  $\leq$  2%.

#### **TYPICAL ELECTRICAL CHARACTERISTICS: PNP Transistor**

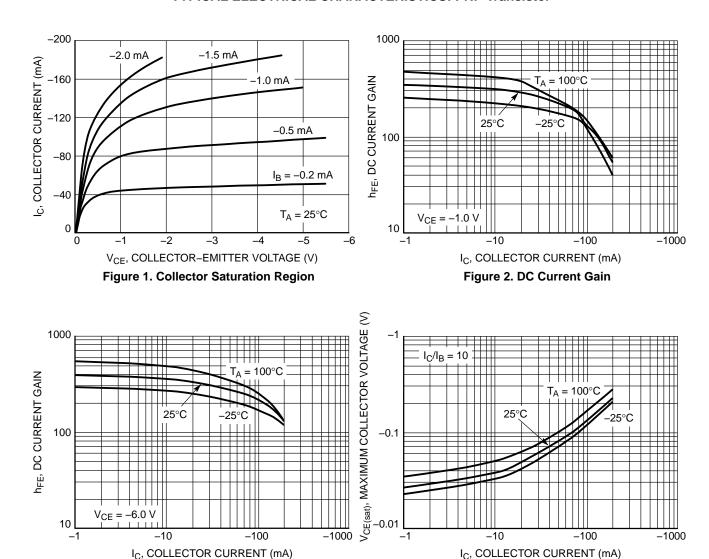
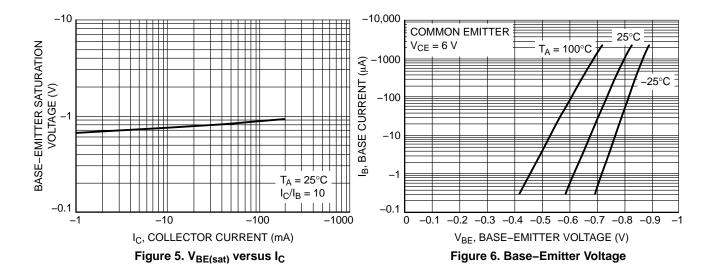


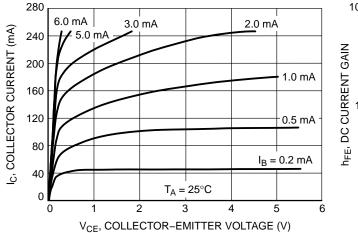
Figure 3. DC Current Gain

Figure 4. V<sub>CE(sat)</sub> versus I<sub>C</sub>



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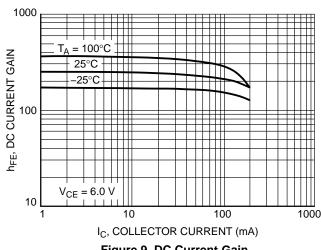
#### **TYPICAL ELECTRICAL CHARACTERISTICS: NPN Transistor**



1000 = 100°C ↓ 25°C | | | | 100  $V_{CE} = 1.0 V$ 10 100 1000 I<sub>C</sub>, COLLECTOR CURRENT (mA)

Figure 7. Collector Saturation Voltage

Figure 8. DC Current Gain



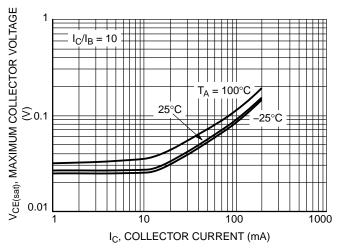
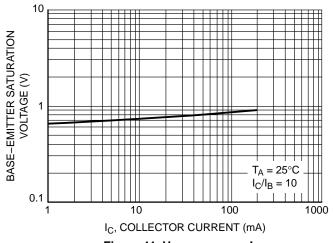


Figure 9. DC Current Gain

Figure 10. V<sub>CE(sat)</sub> versus I<sub>C</sub>



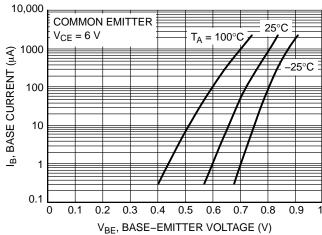


Figure 11. V<sub>BE(sat)</sub> versus I<sub>C</sub>

Figure 12. Base-Emitter Voltage

#### TYPICAL ELECTRICAL CHARACTERISTICS

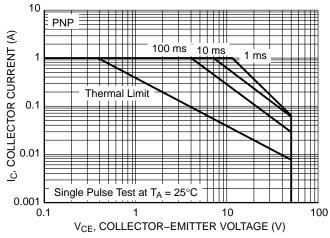


Figure 13. PNP Safe Operating Area

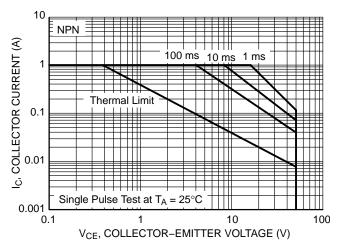


Figure 14. NPN Safe Operating Area





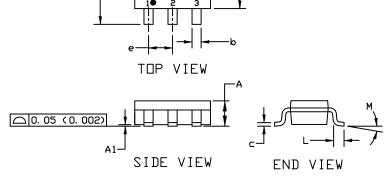
SC-74 CASE 318F ISSUE P

**DATE 07 OCT 2021** 

#### NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994
- 2. CONTROLLING DIMENSION: INCHES
- MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL.

	MI	MILLIMETERS		INCHES		
DIM	MIN.	N□M.	MAX.	MIN.	N□M.	MAX.
Α	0. 90	1. 00	1. 10	0. 035	0. 039	0, 043
A1	0. 01	0. 06	0.10	0. 001	0. 002	0. 004
b	0. 25	0. 37	0. 50	0. 010	0. 015	0. 020
c	0.10	0. 18	0. 26	0. 004	0. 007	0. 010
D	2. 90	3. 00	3. 10	0.114	0. 118	0. 122
E	1. 30	1. 50	1. 70	0. 051	0. 059	0. 067
e	0. 85	0. 95	1. 05	0. 034	0. 037	0. 041
HE	2. 50	2. 75	3. 00	0. 099	0. 108	0. 118
L	0. 20	0. 40	0. 60	0, 008	0. 016	0. 024
М	0*		10*	0*		10*



# GENERIC MARKING DIAGRAM\*

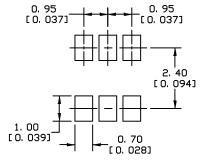


XXX = Specific Device Code M = Date Code

= Pb-Free Package

(Note: Microdot may be in either location)

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.



For additional information on our Pb-Free strategy and soldering details, please download the UN Seniconductor Soldering and Mounting Techniques Reference Manual, SULDERRM/D.

SOLDERING FOOTPRINT

STYLE 1: PIN 1. CATHODE 2. ANODE 3. CATHODE 4. CATHODE 5. ANODE 6. CATHODE	STYLE 2: PIN 1. NO CONNECTION 2. COLLECTOR 3. EMITTER 4. NO CONNECTION 5. COLLECTOR 6. BASE	STYLE 3: PIN 1. EMITTER 1 2. BASE 1 3. COLLECTOR 2 4. EMITTER 2 5. BASE 2 6. COLLECTOR 1	STYLE 4: PIN 1. COLLECTOR 2 2. EMITTER 1/EMITTER 2 3. COLLECTOR 1 4. EMITTER 3 5. BASE 1/BASE 2/COLLECTOR 3 6. BASE 3	STYLE 5: PIN 1. CHANNEL 1 2. ANODE 3. CHANNEL 2 4. CHANNEL 3 5. CATHODE 6. CHANNEL 4	STYLE 6: PIN 1. CATHODE 2. ANODE 3. CATHODE 4. CATHODE 5. CATHODE 6. CATHODE
STYLE 7: PIN 1. SOURCE 1 2. GATE 1 3. DRAIN 2 4. SOURCE 2 5. GATE 2 6. DRAIN 1	STYLE 8: PIN 1. EMITTER 1 2. BASE 2 3. COLLECTOR 2 4. EMITTER 2 5. BASE 1 6. COLLECTOR 1	STYLE 9: PIN 1. EMITTER 2 2. BASE 2 3. COLLECTOR 1 4. EMITTER 1 5. BASE 1 6. COLLECTOR 2	STYLE 10: PIN 1. ANODE/CATHODE 2. BASE 3. EMITTER 4. COLLECTOR 5. ANODE 6. CATHODE	STYLE 11: PIN 1. EMITTER 2. BASE 3. ANODE/CATHOD 4. ANODE 5. CATHODE 6. COLLECTOR	DE

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